

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	5 X 5 X 0.75 (3.14 EP)
Lead Count	28
Terminal Finish	100 Sn
MS Number	MS010602B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	2.38E-02	86.91	869100	38.73		387293
Thermosets	Epoxy & Phenol Resin	Proprietary	3.50E-03	12.78	127800	5.70		56951
Other inorganic materials	Carbon black	1333-86-4	8.50E-05	0.31	3100	0.14		1381
Subtotal			2.74 E-02	100.00	1000000	44.56		445625

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	2.91 E-02	97.50	975000	47.27		472727
Copper & its alloys	Iron	7439-89-6	7.01 E-04	2.35	23500	1.14		11394
Copper & its alloys	Zinc	7440-66-6	3.58 E-05	0.12	1200	0.06		582
Copper & its alloys	Phosphorus	7723-14-0	8.95 E-06	0.03	300	0.01		145
Subtotal			2.98 E-02	100.00	1000000	48.48		484848

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	7.45 E-05	100.0	1000000	0.12		1212

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	1.41 E-03	100.0	1000000	2.29		22880

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	2.12 E-04	99.0	990000	0.35		3452
Precious metals	Palladium	7440-05-3	2.14 E-06	1.0	10000	0.003		35
Subtotal			2.14 E-04	100.0	1000000	0.35		3487

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	2.21 E-03	100.0	1000000	3.60		35955

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	2.84 E-04	77.00	770000	0.46		4614
Other organic materials	Acrylic resin	Proprietary	2.58 E-05	7.00	70000	0.04		419
Other organic materials	Acrylate	Proprietary	2.03 E-05	5.50	55000	0.03		330
Other organic materials	Polybutadiene derivative	Proprietary	1.66 E-05	4.50	45000	0.03		270
Other organic materials	Epoxy resin	Proprietary	9.21 E-06	2.50	25000	0.01		150
Other organic materials	Butadiene Copolymer	Proprietary	5.53 E-06	1.50	15000	0.01		90
Others	Additive	Proprietary	5.53 E-06	1.50	15000	0.01		90
Others	Peroxide	Proprietary	1.84 E-06	0.50	5000	0.003		30
Subtotal			3.69 E-04	100.0	1000000	0.60		5993

Package Totals	Weight (g)	6.15 E-02	Percentage (%)	100	PPM	1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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